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To: Messrs. Epping-Hermann-Fischer  
Patentanwalts-gesellschaft mbH

Application No. 89113563

English language translation for the Publication number 155504  
Publication date: April 1, 1991  
Title: Tape Adhesive and Packaging Apparatus for Golden Fingers of PCB  
Application number: 79210837  
Filing date: September 27, 1990  
Applicant: Acer Computer Co., Ltd

### Claim 1

A tape adhesive and packaging apparatus for golden fingers of PCB, comprising:  
a main body;  
a control device, mounted on the main body;  
a roller PCB transporting device, mounted on the main body;  
a first tape adhesive and packaging device, mounted on the main body and controlled by the control device, for adhering and packaging a tape on a surface of the golden finger of the PCB delivered by the transporting device;  
a tape cutting device, mounted on the first tape adhesive and packaging device and controlled by the control device, for cutting the tape adhered and packaged on the surface of the golden finger in a predetermined length; and  
a second tape adhesive and packaging device, mounted on the main body, for adhering and packaging a tape on a surface of the golden finger of the PCB where has not been adhesive and packaged.

### Brief Description of Drawings

Fig. 1 is a schematic drawing showing tape adhesion and package on the lower surface of the golden finger of PCB,

Fig. 2 is a schematic drawing showing the tape in a case of cutting;

Fig. 3A and 3B are structural and operation drawings showing portion of the cutting tool; and

Fig. 4 is a schematic drawing showing tape adhesion and package on the lower surface of the golden finger of PCB.

## 中華民國專利公報 (19)(12)

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*Utility Model*(11)  
Int: 1.5

H05K 3/00

(51) Int. Cl.: H05K

全 3 頁

(54) 名稱: 印刷電路板金手指帶貼封裝置 *Title*

(21)申請案號: 79210837

(22)申請日期: 中華民國78年(1990)09月27日

*Application No.**Filing date*

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(57)申請專利範圍:

1. 一種印刷電路板金手指帶貼封裝置, 包括有:
  - 一主體;
  - 一控制裝置, 其裝設於主體上;
  - 一復捲式印刷電路板輸送裝置, 其裝設於主體上;
  - 第一膠帶貼封裝置, 其裝設於主體上, 受控制裝置之控制, 將由輸送裝置送來印刷電路板金手指之一表面予以貼封膠帶;
  - 一膠帶切斷裝置, 其裝設於第一膠帶貼封裝置上, 其受控制裝置之控制, 將已貼封於金手指表面的膠帶依設定的長度切斷;

第二膠帶貼封裝置, 其裝設於主體上, 將由輸送裝置送來之印刷電路板金手指尚未貼封之一面予以貼封膠帶。

圖示簡要說明:

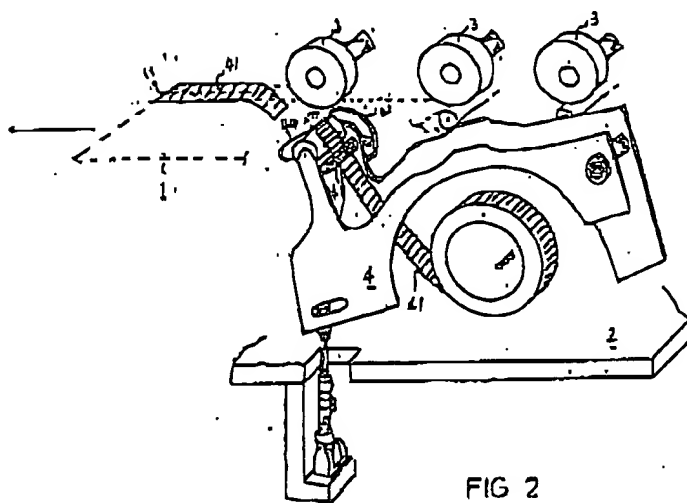
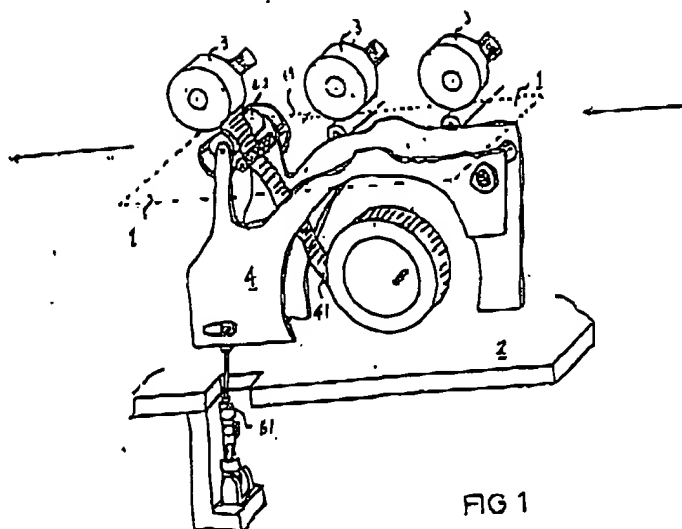
第1圖為印刷電路板金手指下表面膠帶貼封之示意圖。

第2圖為貼封膠帶板切斷時之示意圖。

第3(A)(B)圖為切割刀具部份之構造及動作圖。

第4圖為印刷電路板金手指下表面膠帶貼封之示意圖。

(2)



(3)

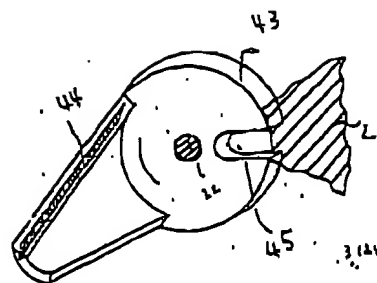
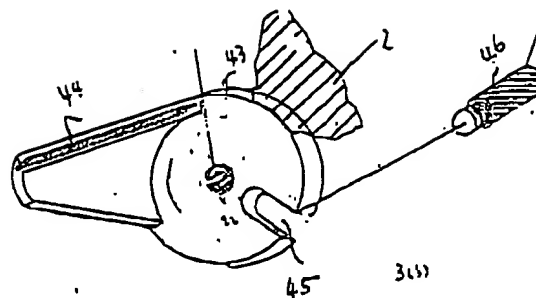


FIG 3

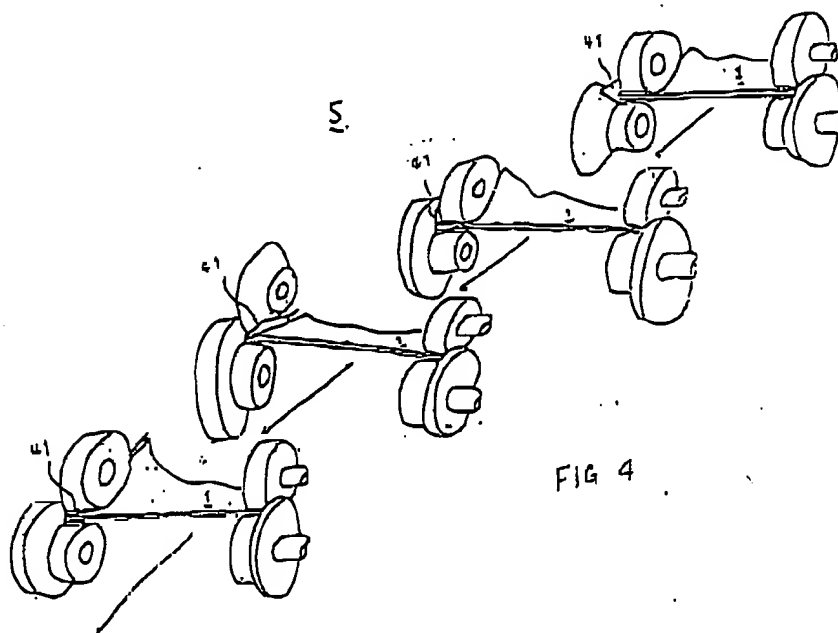


FIG 4